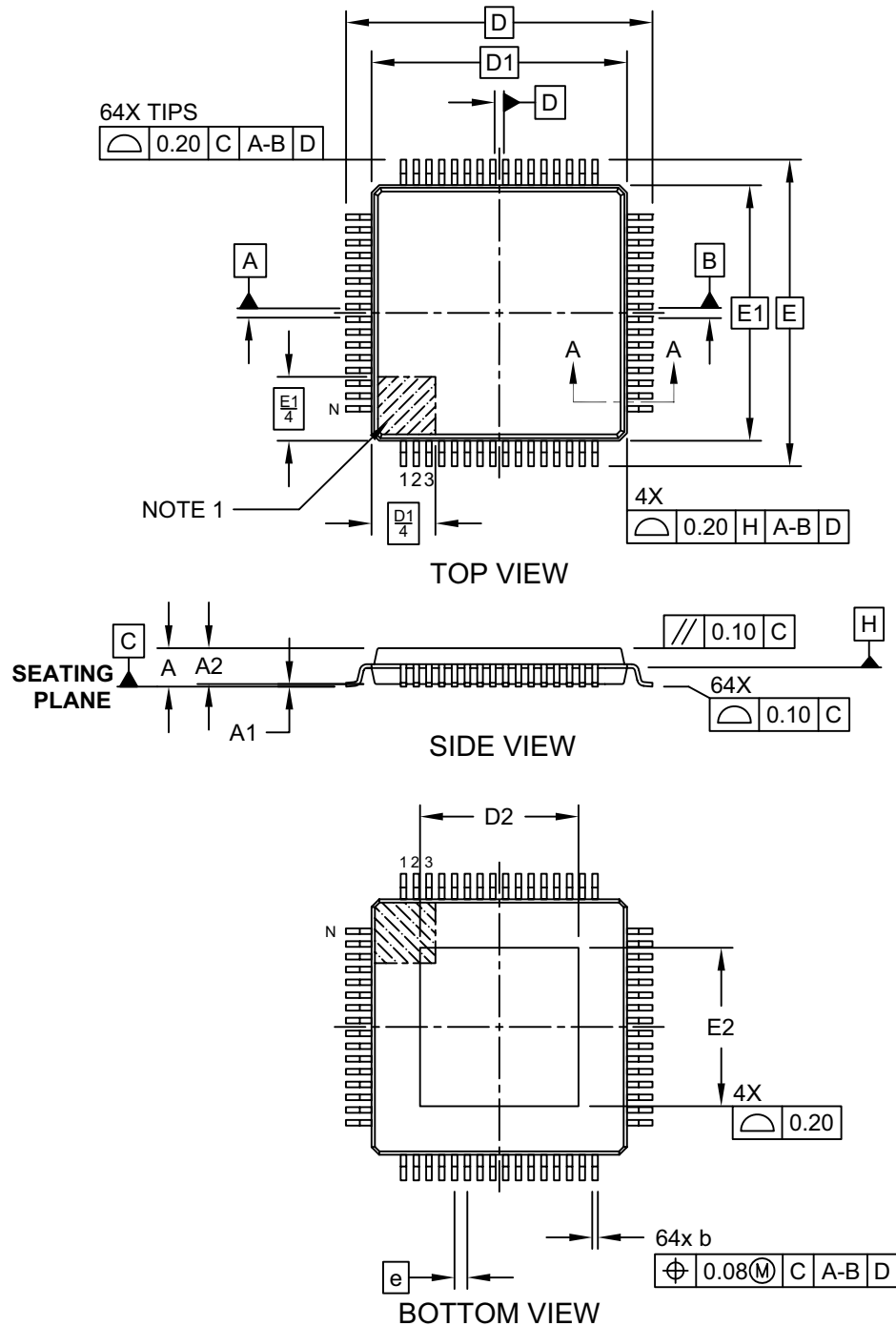


**64-Lead Low-Profile Plastic Quad Flat Pack Package (CFA) -10x10 mm Body [LQFP]  
With 6.2x6.2 mm Exposed Pad and 2.0 mm Foot Print; Micrel Legacy**

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

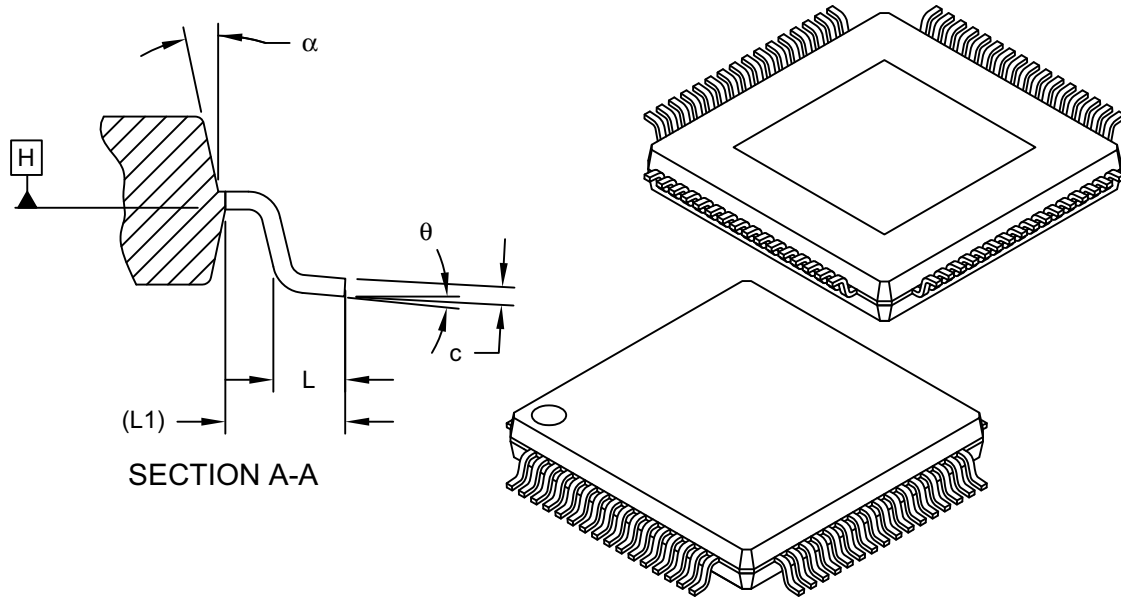




# MICROCHIP

## 64-Lead Low-Profile Plastic Quad Flat Pack Package (CFA) -10x10 mm Body [LQFP] With 6.2 mm Exposed Pad and 2.0 mm Foot Print; Micrel Legacy

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Leads	N	64		
Lead Pitch	e	0.50 BSC		
Overall Height	A	-	-	1.60
Standoff	A1	0.05	0.10	0.15
Molded Package Thickness	A2	1.35	1.40	1.45
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	θ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Exposed Pad Width	E2	6.10	6.20	6.30
Exposed Pad Length	D2	6.10	6.20	6.30
Lead Width	b	0.17	0.22	0.27
Lead Thickness	c	0.09	-	0.20
Mold Draft Angle Top	α	11°	12°	13°

**Notes:**

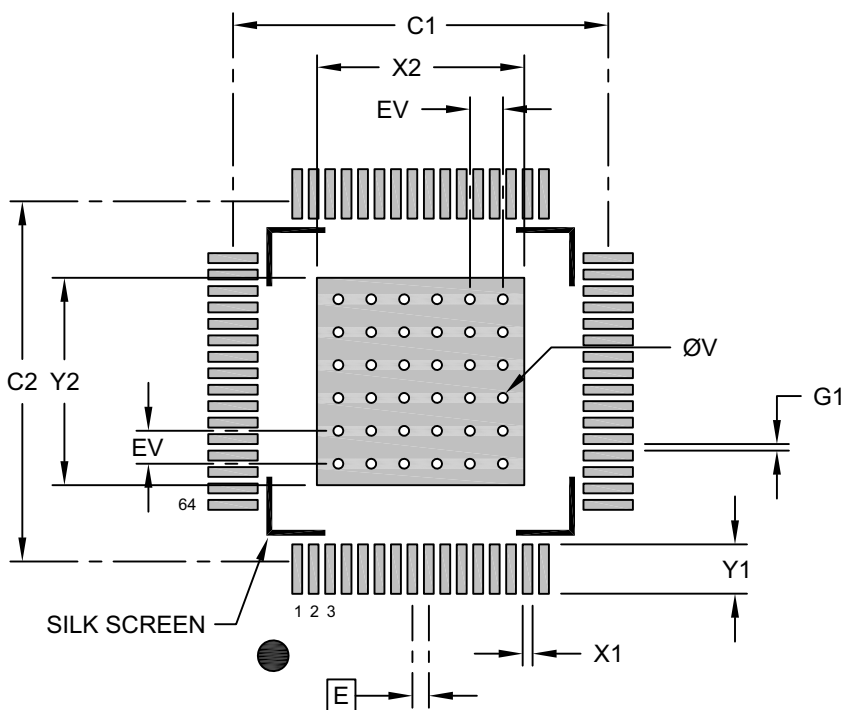
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

**64-Lead Low-Profile Plastic Quad Flat Pack Package (CFA) -10x10 mm Body [LQFP]  
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**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



**RECOMMENDED LAND PATTERN**

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			6.30
Optional Center Pad Length	Y2			6.30
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Contact Pad to Contact Pad (X60)	G1	0.20		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

**Notes:**

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process